

Pan
Serial no. 10/013,089
Attorney docket no. 67,200-627

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Listing of Claims

1. (currently amended) A housing to receive a semiconductor wafer tray comprising:
at least four discrete-positioning kits extending from interior sidewalls of the housing,
each positioning kit comprising:
a primary outside edge at least substantially corresponding to one of the an
interior sidewallS of the housing; and,
an inside edge opposite of the primary outside edge, and having a groove at least
substantially corresponding to a part of a frame of the semiconductor wafer tray,
the groove receptive to the part of the frame of the semiconductor wafer tray, to
assist maintaining the semiconductor wafer tray in a stable position when the semiconductor
wafer tray is completely positioned in the housing, wherein the housing comprises a quartz tube
for a semiconductor fabrication rapid thermal process (RTP),
~~wherein at least one of the four positioning kits each extend from a back interior sidewall~~
~~of the interior sidewallS of the housing, at least one of the four positioning kits each extend from~~
~~a first side interior sidewall of the interior sidewallS of the housing, and at least one of the four~~
~~positioning kits each extend from a second side interior sidewall of the interior sidewallS of the~~
~~housing, the second side interior sidewall opposite to the first side interior sidewall;~~
2. (original) The housing of claim 1, wherein each positioning kit further comprises:
an upper outside edge facing an interior upper wall of the housing; and,
a lower outside edge facing an interior lower wall of the housing.
3. (original) The housing of claim 1, wherein the primary outside edge of each positioning
kit is fixed to the interior sidewall of the housing to which the primary outside edge at least
substantially corresponds.

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4. (original) The housing of claim 1, wherein the groove of the inside edge of each positioning kit is shaped to mirror the part of the frame of the semiconductor wafer tray to which the groove substantially corresponds, such that the part of the frame fits snugly inside the groove.
5. (original) The housing of claim 1, wherein the groove is substantially rectangular in shape.
6. (original) The housing of claim 1, wherein each positioning kit is substantially shaped like a letter C.
- 7.-13. (cancelled)

14. (previously presented) A semiconductor fabrication rapid thermal processing (RTP) assembly comprising:

a reactor block having a slot therein;
a tube fitting in the slot of the reactor block;
a wafer tray accepting a semiconductor wafer on which RTP is to be performed, the tray slidable into and out of the tube; and,

at least four discrete positioning kits fixed inside the tube and extending from interior sidewalls of the tube, each positioning kit having a groove at least substantially corresponding to a part of the wafer tray and receptive to the part of the wafer tray when the tray is slid into the tube to assist maintaining the tray in a stable position within the tube during the RTP,

wherein at least one of the four positioning kits each extend from a back interior sidewall of the interior sidewalls of the tube, at least one of the four positioning kits each extend from a first side interior sidewall of the interior sidewalls of the tube, and at least one of the four positioning kits each extend from a second side interior sidewall of the interior sidewalls of the tube, the second side interior sidewall opposite to the first side interior sidewall.

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15. (original) The assembly of claim 14, wherein the groove of each positioning kit is shaped to mirror the part of the wafer tray to which the groove substantially corresponds, such that the part of the frame fits snugly inside the groove.

16. (cancelled)

17. The assembly of claim 14, wherein the RTP comprises rapid thermal annealing (RTA).

18. 20. (cancelled)